

SL-SMT 5.08HC/04/90 1.5AU BK RL CO**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



Similar to illustration

High-temperature-resistant, straight, open pin header.
Packed in box or tape. On tape and with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 5.08 mm, Number of poles: 4, 90°, Solder pin length (l): 1.5 mm, Gold-plated, black, Tape
Order No.	1408550000
Type	SL-SMT 5.08HC/04/90 1.5AU BK RL CO
GTIN (EAN)	4050118209242
Qty.	350 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Tape

Creation date March 23, 2021 9:32:44 PM CET

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Technical data

Dimensions and weights

Depth	12 mm	Depth (inches)	0.472 inch
Height	10 mm	Height (inches)	0.394 inch
Height of lowest version	8.5 mm	Net weight	2.326 g
Width	20.32 mm	Width (inches)	0.8 inch

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5.08 mm
Pitch in inches (P)	0.2 inch	Outgoing elbow	90°
Number of poles	4	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tolerance (D)+	0,1 mm	L1 in mm	15.24 mm
L1 in inches	0.6 inch	Pin series quantity	1
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	9 N	Pulling force/pole, max.	7 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface	Gold-plated	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn / 1.7...2.3 µm Au	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	18.5 A	Rated current (Use group D / CSA)	18.5 A

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Technical data

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 18.5 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Packing

Packaging	Tape	VPE length	50 mm
VPE width	330 mm	VPE height	330 mm
Tape depth (T2)	12.8 mm	Tape width (W)	44 mm
Tape pocket depth (K0)	12.3 mm	Tape pocket height (A0)	12.3 mm
Tape pocket width (B0)	20.42 mm	Tape pocket separation (P1)	16 mm
Tape hole separation (E)	1.75 mm	Tape pocket separation (F)	20.2 mm
Tape reel diameter Ø (A)	330 mm	Surface resistance	$R_s = 10^9 - 10^{12} \Omega$

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Important note

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Gold-plated contact surfaces on request
- Rated current related to rated cross-section & min. No. of poles.
- Diameter of solder eyelet $D = 1.4 + 0.1 \text{ mm}$
- Solder eyelet diameter $D = 1.5 + 0.1 \text{ mm}$, from 9 poles
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



ROHS

Conform

UL File Number Search

E60693

Creation date March 23, 2021 9:32:44 PM CET

Catalogue status 12.03.2021 / We reserve the right to make technical changes.

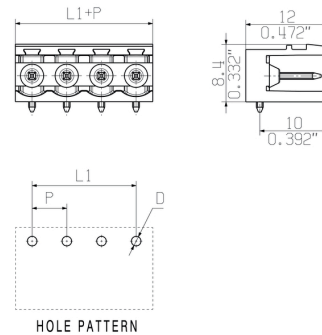
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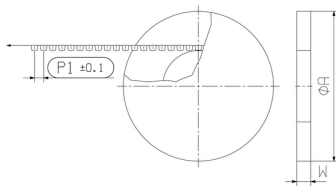
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Drawings

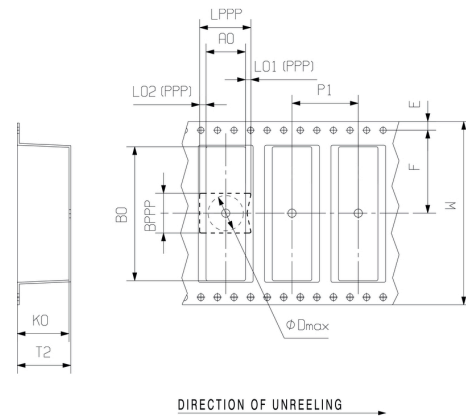
Dimensional drawing



Dimensional drawing



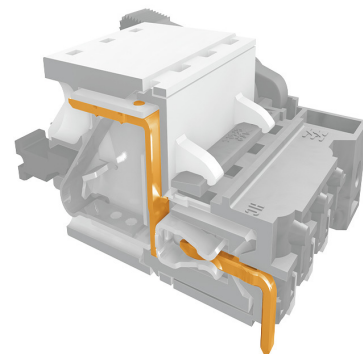
Dimensional drawing



Example of use



Product benefits



Safe power transmission
Proven properties

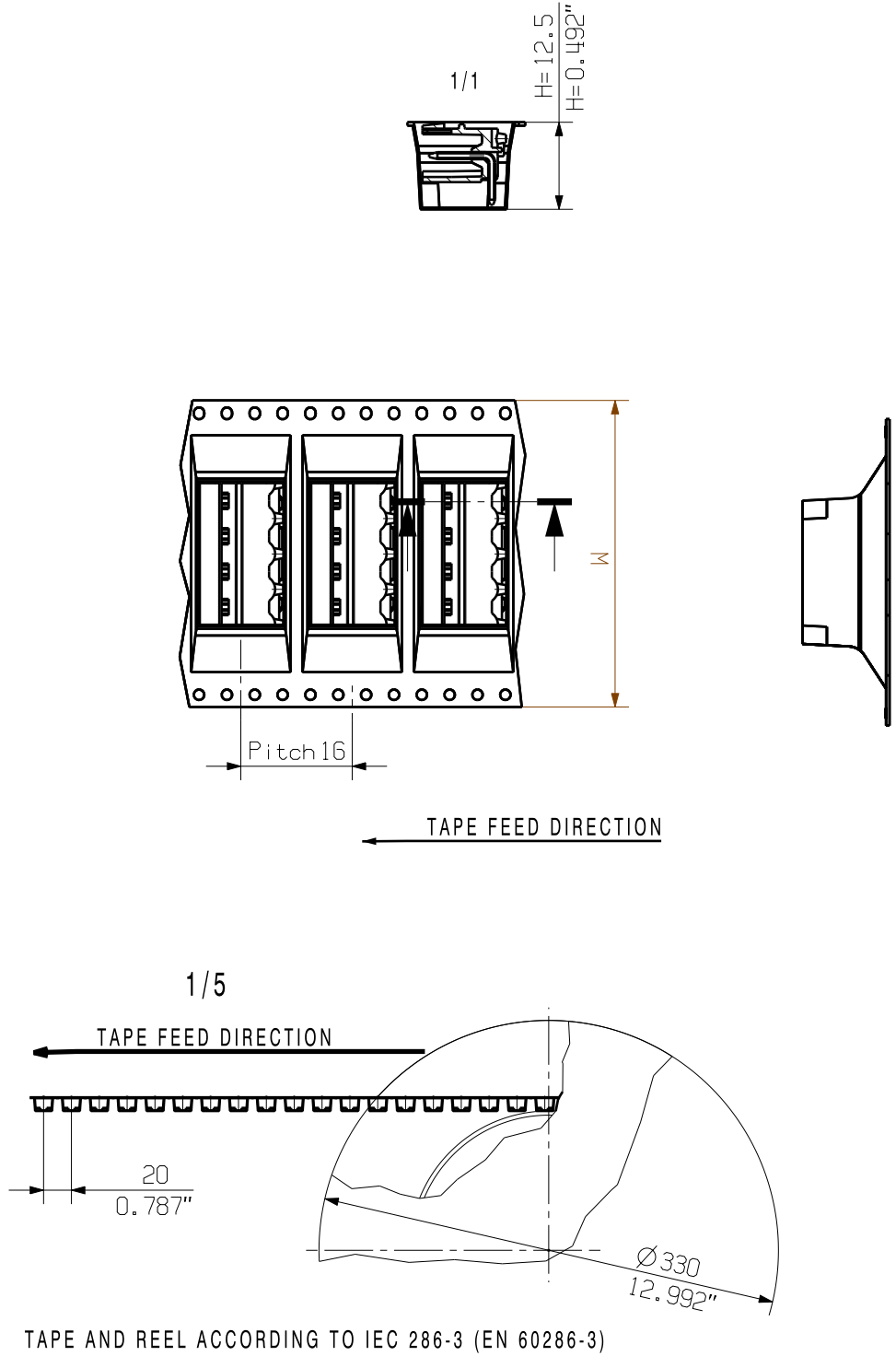
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WEIDMUELLER INTERFACE GmbH & Co.KG

MASS E OHNE TOLERANZ SIND KEINE PRUEFFMASSE
DIMS. WITHOUT TOLERANCE ARE NOT CONTROL DIMS.

DIE DEUTSCHE VERSION IST VERBINDLICH
THE GERMAN VERSION IS BINDING

BEZEICHNUNG	W (TAPEBREITE)	W (TAPE WIDTH)
	[mm]	[inch]
Tape32 SL5.08/2 90	32,00	1,26
Tape32 SL5.08/3 90	32,00	1,26
Tape44 SL5.08/4/2F/90	44,00	1,73
Tape44 SL5.08/5/3F/90	44,00	1,73
Tape44 SL5.08/6/4F/90	44,00	1,73
Tape56 SL5.08/7/5F/90	56,00	2,20
Tape56 SL5.08/8/6F/90	56,00	2,20
Tape72 SL5.08/9/7F/90	72,00	2,83
Tape72 SL5.08/10/8F/90	72,00	2,83
Tape72 SL5.08/11/9F/90	72,00	2,83
Tape88 SL5.08/12/10F/90	88,00	3,46
Tape88 SL5.08/13/11F/90	88,00	3,46
Tape88 SL5.08/14/12F/90	88,00	3,46
Tape32 SL5.08/2G 90	32,00	1,26
Tape32 SL5.08/3G 90	32,00	1,26
Tape44 SL5.08/4G 90	44,00	1,73
Tape44 SL5.08/5G 90	44,00	1,73
Tape44 SL5.08/6G 90	44,00	1,73
Tape56 SL5.08/7G 90	56,00	2,20
Tape56 SL5.08/8G90	56,00	2,20
Tape72 SL5.08/9G 90	72,00	2,83
Tape72 SL5.08/10G 90	72,00	2,83
Tape88 SL5.08/11G 90	88,00	3,46
Tape88 SL5.08/12G 90	88,00	3,46
Tape88 SL5.08/13G 90	88,00	3,46



For the mounting of PCBs, it should be noted that the rated data stated here relates only to the PCB components alone.
The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.
The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.
Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

	DIN ISO 2768-m				CAT.NO.: .	
	73540/0 28.01.15 HELIS_MA		00			
MODIFICATION		DATE	NAME	 C 29867 28 DRAWING NO. SHEET 01 OF 01 SHEETS ISSUE NO. SL-SMT 5.08HC/././90...RL STIFTLISTE MALE HEADER PRODUCT FILE: SL-SMT 5.08 7280		
DRAWN		17.07.2008	HELIS_MA			
RESPONSIBLE			HERTEL_S			
CHECKED		03.02.2015	HELIS_MA			
SCALE: 2/1 SUPERSEDES: .		APPROVED	LANG_T			

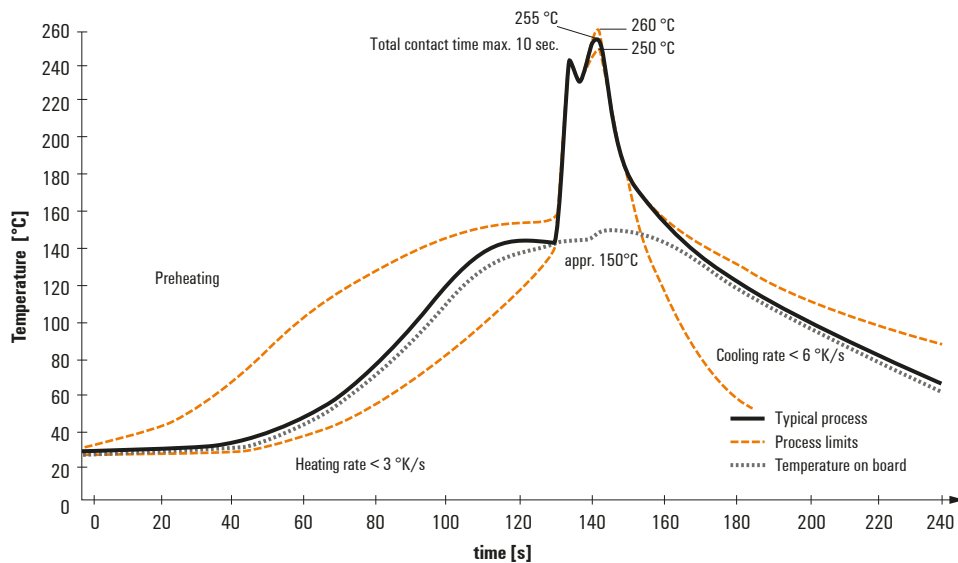
Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

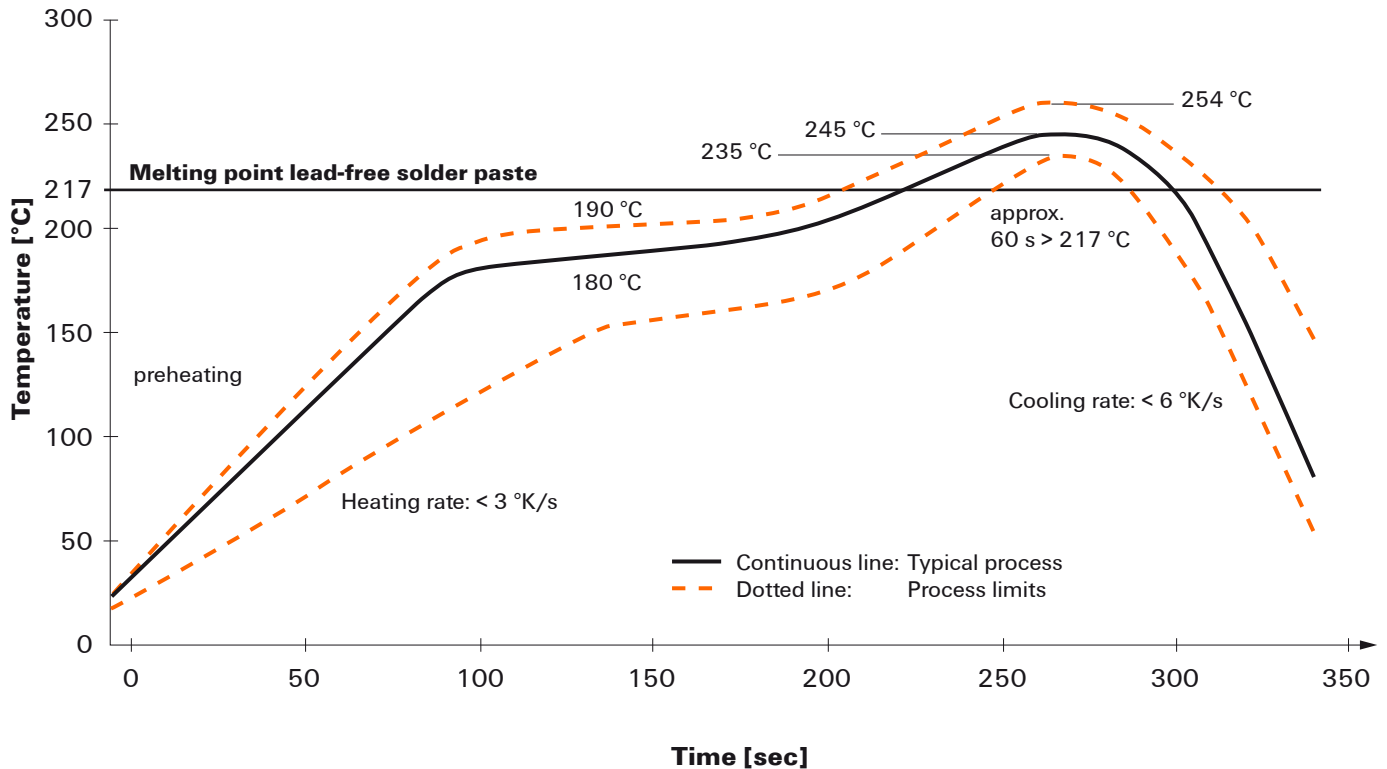
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260 °C . In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.